TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π -MOSIV)

2SK3799

Switching Regulator Applications

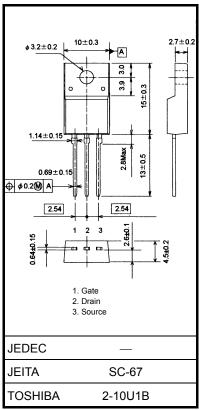
Unit: mm

• Low drain-source ON resistance : RDS (ON) = 1.0Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 6.0 S$ (typ.) • Low leakage current : IDSS = 100μ A (max) (VDS = 720 V)

• Enhancement model : $V_{th} = 2.0 \text{ to } 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	900	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	900	V	
Gate-source voltage		V_{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	8	Α	
	Pulse (Note 1)	I _{DP}	24	Α	
Drain power dissipation		P _D	50	W	
Single pulse avalanche energy (Note 2)		E _{AS}	1080	mJ	
Avalanche current		I _{AR}	8	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

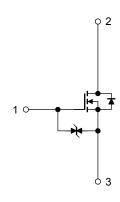
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.5	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C during use of the device.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 30.9 mH, R_G = 25 Ω , I_{AR} = 8 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature.

This transistor is an electrostatic-sensitive device. Handle with care.





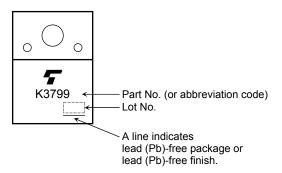
Electrical Characteristics (Ta = 25°C)

Chara	cteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	irrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain-source bre	eakdown voltage	V (BR) GSS	I_{G} = ±10 μ A, V_{GS} = 0 V	±30	_	_	V
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V		_	100	μΑ
Drain-source bro	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	450	_	_	V
Gate threshold v	oltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source Of	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 4 A		1.0	1.3	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 15 V, I _D = 4 A	3.5	6.0	_	S
Input capacitano	e	C _{iss}			2200	_	pF
Reverse transfe	r capacitance	C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		45	_	
Output capacitance		Coss]		190	_]
Switching time	Rise time	t _r	V _{DD} ≈ 400 V	_	25	_	
	Turn-on time	ton		_	65	_	ns
	Fall time	t _f		_	20	_	
	Turn-off time	t _{off}	Duty ≤ 1%, t _w = 10 μs		120	_	
Total gate charge (Gate-source plus gate-drain)		Qg	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 8 A		60	_	nC
Gate-source charge		Q _{gs}			34		
Gate-drain ("miller") charge		Q _{gd}			26		

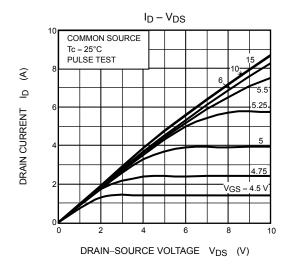
Source-Drain Ratings and Characteristics (Ta = 25°C)

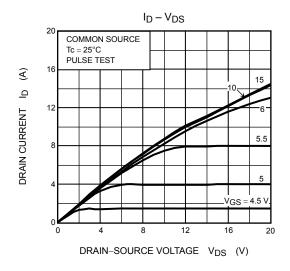
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	8	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-	_	_	24	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 8 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 8 A, V _{GS} = 0 V	_	1700	_	ns
Reverse recovery charge	Qrr	dI_{DR} / $dt = 100 A / \mu S$	_	23	_	μС

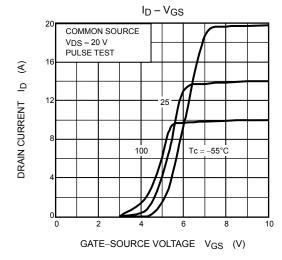
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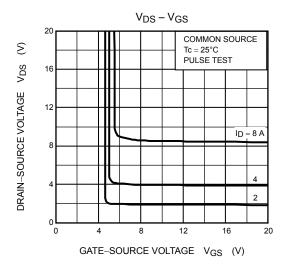


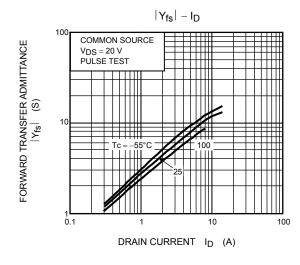
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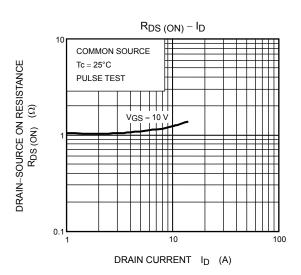


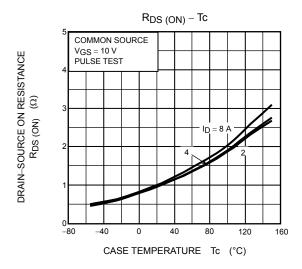


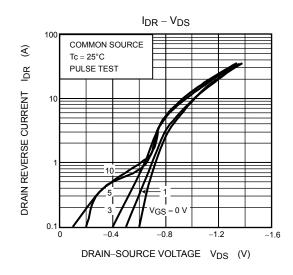


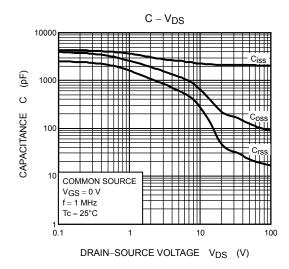


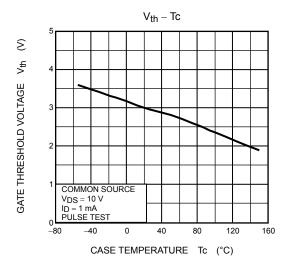


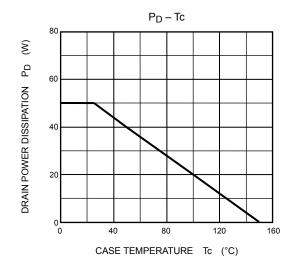


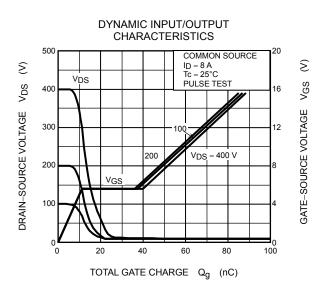


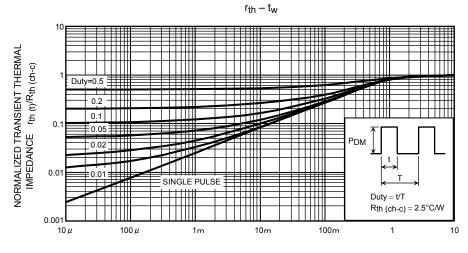




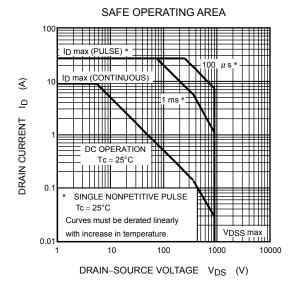


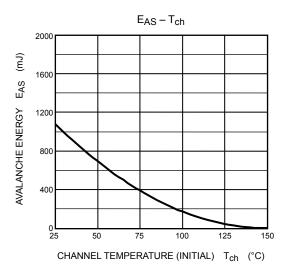


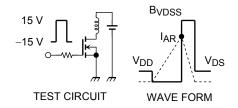




PULSE WIDTH t_w (s)







$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 30.9~mH \end{aligned} \quad \text{EAS} = 0.00$$

$$EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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